



DMTH6016LPSQ

#### 60V 175°C N-CHANNEL ENHANCEMENT MODE MOSFET POWERDI

### **Product Summary**

| BV <sub>DSS</sub> | Rds(on)                       | Ι <sub>D</sub><br>T <sub>C</sub> = +25°C |
|-------------------|-------------------------------|--|
| 60V               | 16mΩ @ V <sub>GS</sub> = 10V  | 37A                                      |
|                   | 24mΩ @ V <sub>GS</sub> = 4.5V | 29A                                      |

# **Description and Applications**

This MOSFET has been designed to meet the stringent requirements of Automotive applications. It is qualified to AEC-Q101, supported by a PPAP and is ideal for use in:

- **Power Management**
- DC-DC Converters
- Motor Control

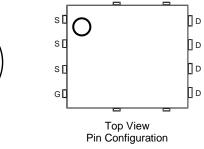
#### Features

- Rated to +175°C Ideal for High Ambient Temperature **Environments**
- Thermally Efficient Package Cooler Running Applications
- High Conversion Efficiency
- Low R<sub>DS(ON)</sub> Minimizes On-State Losses
- Low Input Capacitance
- Fast Switching Speed
- <1.1mm Package Profile Ideal for Thin Applications
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability
- PPAP Capable (Note 4)

### **Mechanical Data**

- Case: PowerDI5060-8
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Finish Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 @3
- Weight: 0.097 grams (Approximate)





### Ordering Information (Note 5)

| Part Number     | Case          | Packaging           |
|-----------------|---------------|---------------------|
| DMTH6016LPSQ-13 | PowerDI5060-8 | 2,500 / Tape & Reel |

1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied. Notes:

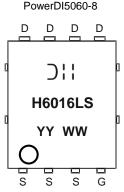
2. See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. Automotive products are AEC-Q101 qualified and are PPAP capable. Refer to http://www.diodes.com/product\_compliance\_definitions.html.

5. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

### Marking Information



DLL = Manufacturer's Marking H6016LS = Product Type Marking Code YYWW = Date Code Marking YY = Last Two Digits of Year (ex: 16 = 2016) WW = Week Code (01 to 53)



# Maximum Ratings (@T<sub>A</sub> = +25°C, unless otherwise specified.)

| Characteristic  | Symbol  | Value          | Unit       |   |
|---|---|----------------|------------|---|
| Drain-Source Voltage                                    | V <sub>DSS</sub>                                  | 60             | V          |   |
| Gate-Source Voltage                                     | V <sub>GSS</sub>                                  | ±20            | V          |   |
| Continuous Drain Current (Note 7) V <sub>GS</sub> = 10V | T <sub>C</sub> = +25°C<br>T <sub>C</sub> = +100°C | ID             | 37<br>30.3 | A |
| Continuous Drain Current (Note 6) $V_{GS}$ = 10V        | $T_A = +25^{\circ}C$ $T_A = +100^{\circ}C$        | I <sub>D</sub> | 9.8<br>6.9 | A |
| Pulsed Drain Current (10µs pulse, duty cycle = 1%)      | I <sub>DM</sub>                                   | 75             | A          |   |
| Maximum Continuous Body Diode Forward Current (Note 7)  | Is  | 31             | A          |   |
| Avalanche Current, L = 0.1mH                            | I <sub>AS</sub>                                   | 15.3           | A          |   |
| Avalanche Energy, L = 0.1mH                             | Eas   | 11.7           | mJ         |   |

### **Thermal Characteristics**

| Characteristic                                   |                        | Symbol           | Value       | Unit |
|--|------------------------|------------------|-------------|------|
| Total Power Dissipation (Note 6)                 | T <sub>A</sub> = +25°C | PD               | 2.6         | W    |
| Thermal Resistance, Junction to Ambient (Note 6) |                        | R <sub>θJA</sub> | 57          | °C/W |
| Total Power Dissipation (Note 7)                 | T <sub>C</sub> = +25°C | PD               | 37.5        | W    |
| Thermal Resistance, Junction to Case (Note 7)    |                        | R <sub>θJC</sub> | 4           | °C/W |
| Operating and Storage Temperature Range          |                        | TJ, TSTG         | -55 to +175 | °C   |

# Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

| Characteristic                             | Symbol              | Min | Тур | Max  | Unit  | Test Condition  |  |
|--|---------------------|-----|-----|------|-------|---|--|
| OFF CHARACTERISTICS (Note 8)               | •                   |     |     | •    |       |   |  |
| Drain-Source Breakdown Voltage             | BV <sub>DSS</sub>   | 60  | -   | _    | V     | $V_{GS} = 0V, I_{D} = 250 \mu A$                            |  |
| Zero Gate Voltage Drain Current            | I <sub>DSS</sub>    | —   | _   | 1    | μA    | $V_{DS} = 48V, V_{GS} = 0V$                                 |  |
| Gate-Source Leakage                        | Igss                | —   | _   | ±100 | nA    | $V_{GS} = \pm 20V, V_{DS} = 0V$                             |  |
| ON CHARACTERISTICS (Note 8)                | •                   |     | •   |      |       |   |  |
| Gate Threshold Voltage                     | V <sub>GS(TH)</sub> | 1   | _   | 2.5  | V     | $V_{DS} = V_{GS}$ , $I_D = 250 \mu A$                       |  |
| Static Drain-Source On-Resistance          |                     | _   | 12  | 16   | mΩ    | $V_{GS} = 10V, I_D = 20A$                                   |  |
| Static Drain-Source On-Resistance          | R <sub>DS(ON)</sub> | _   | 21  | 24   | 11175 | V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 18A                |  |
| Diode Forward Voltage                      | V <sub>SD</sub>     | —   | 0.7 | 1.2  | V     | $V_{GS} = 0V, I_S = 1A$                                     |  |
| DYNAMIC CHARACTERISTICS (Note 9)           | •                   |     | •   |      |       |   |  |
| Input Capacitance                          | Ciss                | _   | 864 | —    |       | $V_{DS} = 30V, V_{GS} = 0V,$<br>f = 1MHz                    |  |
| Output Capacitance                         | Coss                | —   | 282 | _    | pF    |   |  |
| Reverse Transfer Capacitance               | Crss                | —   | 27  | _    |       |   |  |
| Gate Resistance                            | R <sub>G</sub>      | —   | 1.3 | _    | Ω     | $V_{DS} = 0V, V_{GS} = 0V, f = 1MHz$                        |  |
| Total Gate Charge (V <sub>GS</sub> = 4.5V) | Qg                  | _   | 8.4 | _    |       |   |  |
| Total Gate Charge (V <sub>GS</sub> = 10V)  | Qg                  | —   | 17  | _    | nC    | $V_{DS} = 30V, I_D = 10A$                                   |  |
| Gate-Source Charge                         | Q <sub>gs</sub>     | _   | 3.1 | _    | nc    |   |  |
| Gate-Drain Charge                          | Q <sub>gd</sub>     | _   | 4.3 | _    |       |   |  |
| Turn-On Delay Time                         | t <sub>D(ON)</sub>  | _   | 3.4 | _    |       | $V_{GS} = 10V, V_{DS} = 30V,$<br>$R_G = 6\Omega, I_D = 10A$ |  |
| Turn-On Rise Time                          | t <sub>R</sub>      | _   | 5.2 | _    |       |   |  |
| Turn-Off Delay Time                        | t <sub>D(OFF)</sub> | _   | 13  | _    | ns    |   |  |
| Turn-Off Fall Time                         | t <sub>F</sub>      | _   | 7   | _    |       |   |  |
| Reverse Recovery Time                      | t <sub>RR</sub>     | _   | 22  | _    | ns    |   |  |
| Reverse Recovery Charge                    | Q <sub>RR</sub>     | —   | 11  | —    | nC    | I <sub>F</sub> = 10A, di/dt = 100A/µs                       |  |

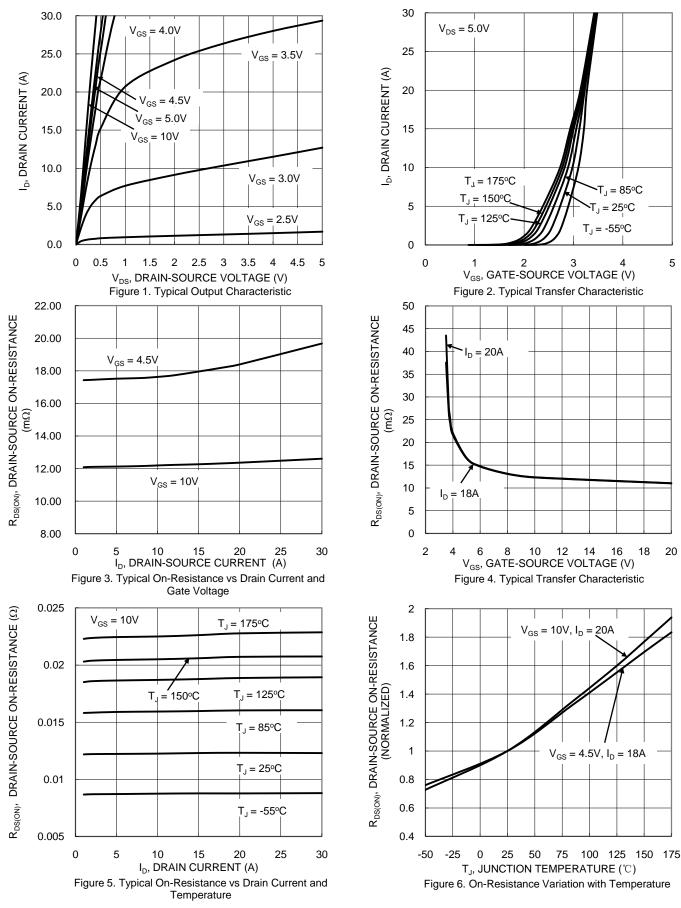
Notes: 6. Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1-inch square copper plate.

Thermal resistance from junction to soldering point (on the exposed drain pad).
Short duration pulse test used to minimize self-heating effect.

9. Guaranteed by design. Not subject to product testing.



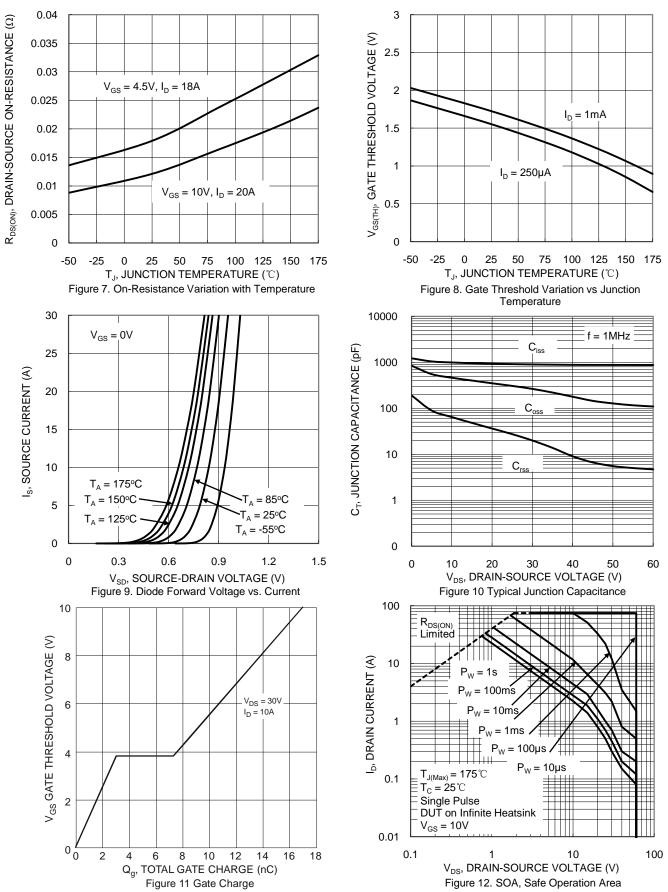
### DMTH6016LPSQ



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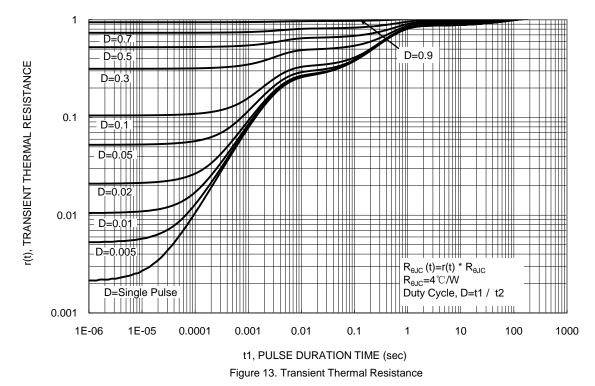
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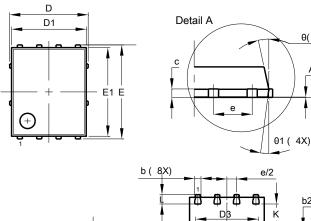
# **Package Outline Dimensions**

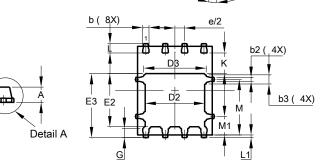
Please see http://www.diodes.com/package-outlines.html for the latest version.

#### PowerDI5060-8

θ( 4X)

A1



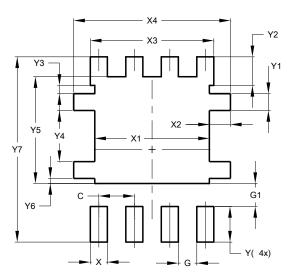


| PowerDI5060-8 |                      |          |                 |  |  |
|---------------|----------------------|----------|-----------------|--|--|
| Dim           | Min                  | Max      | Тур             |  |  |
| Α             | 0.90                 | 1.10     | 1.00            |  |  |
| A1            | 0.00                 | 0.05     | -               |  |  |
| b             | 0.33                 | 0.51     | 0.41            |  |  |
| b2            | 0.200                | 0.350    | 0.273           |  |  |
| b3            | 0.40                 | 0.80     | 0.60            |  |  |
| С             | 0.230                | 0.330    | 0.277           |  |  |
| D             |                      | 5.15 BSC |                 |  |  |
| D1            | 4.70                 | 5.10     | 4.90            |  |  |
| D2            | 3.70                 | 4.10     | 3.90            |  |  |
| D3            | 3.90                 | 4.30     | 4.10            |  |  |
| E             | 6.15 BSC             |          |                 |  |  |
| E1            | 5.60                 | 6.00     | 5.80            |  |  |
| E2            | 3.28                 | 3.68     | 3.48            |  |  |
| E3            | 3.99                 | 4.39     | 4.19            |  |  |
| е             | 1.27 BSC             |          |                 |  |  |
| G             | 0.51                 | 0.71     | 0.61            |  |  |
| K             | 0.51                 | -        | -               |  |  |
| L             | 0.51                 | 0.71     | 0.61            |  |  |
| L1            | 0.100                | 0.200    | 0.175           |  |  |
| Μ             | 3.235                | 4.035    | 3.635           |  |  |
| M1            | 1.00                 | 1.40     | 1.21            |  |  |
| Θ             | 10°                  | 12º      | 11 <sup>0</sup> |  |  |
| Θ1            | 6°                   | 8º       | 7°              |  |  |
| Al            | All Dimensions in mm |          |                 |  |  |

## Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### PowerDI5060-8



| Dimensions | Value (in mm) |  |  |
|------------|---------------|--|--|
| С          | 1.270         |  |  |
| G          | 0.660         |  |  |
| G1         | 0.820         |  |  |
| Х          | 0.610         |  |  |
| X1         | 4.100         |  |  |
| X2         | 0.755         |  |  |
| X3         | 4.420         |  |  |
| X4         | 5.610         |  |  |
| Y          | 1.270         |  |  |
| Y1         | 0.600         |  |  |
| Y2         | 1.020         |  |  |
| Y3         | 0.295         |  |  |
| Y4         | 1.825         |  |  |
| Y5         | 3.810         |  |  |
| Y6         | 0.180         |  |  |
| Y7         | 6.610         |  |  |



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